

Amendments to the Specification are as follows:

Before the first sentence on page 1 please insert the following paragraph.

This application claims the benefit of priority to Japanese Patent Application No. 2003-068645, herein incorporated by reference.

Please amend the paragraph beginning on page 2, line 14 and ending on page 2 line 21 as follows:

Therefore, the overcoat film 55 not only fails to protect the wire 53 and causes breaking of the wire 53 when external force is applied, but also, even if the semiconductor device is mounted on a predetermined place by a mounting machine, the overcoat film 55 cracks when adsorption is applied to it by ana adsorption unit of the mounting machine. As a result, it is impossible to mount the semiconductor device using the mounting machine.

Please amend the paragraph beginning on page 8, line 12 and ending on page 8, line 18 as follows:

Also, the outer surface 5a of the protection member 5 is flat and is parallel to the surface 1a of the substrate 1. An adsorption unit (not shown) of a mounting machine (not shown) is applied to the outer surface 5a and mounts the electronic circuit unit on a predetermined place while applying adsorption to the electronic circuit unit.